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chip (52) having connection pads (50) in the form of microspheres, said card (CP) comprising a substrate (10) formed by a flexible insulating film equipped with conducting tracks electrically connected to tip contacts (26) designed to come into engagement with said connection pads (50) when testing is performed,

- 5 wherein the flexible film is mounted on a truncated part (30c) of a support part (30) operating in conjunction with a guide (43) associated to a spring suspension (46) so as to obtain a uniform distribution of the contact pressure of the tips (26) on all the connection pads (50) without lateral friction, and that correction of the alignment fault between the plane of the support printed circuit (32) and the plane of the tips (26) is
- 10 performed by means of a correcting system (31) with three support points adjustable by screws (40) acting on the base (30a) of the support part (30).

8. The card with multiple tips according to claim 7, wherein the support part (30) comprises a cylindrical intermediate part (30b) arranged coaxially inside the guide (29)
- 15 and having a diameter smaller than that of the base (30a).

9. The card with multiple tips according to one of the claims 7 or 8, wherein the truncated part (30c) of the support part (30) is provided with a window (38) equipped with a plate made of transparent material, glass or quartz, allowing visual testing of the
- 20 ~~alignment of the tips (26) on the connection pads (50) of the semi-conductor chip (52).~~

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